



PRESS RELEASE

Palomar Technologies offers Webinar on How to Increase Semiconductor Packaging Throughput

Free Webinar: June 29, at 8 am PST

Carlsbad, CA – June 6, 2022 – [Palomar Technologies](https://www.palomartechnologies.com), a global leader in delivering total process solutions for advanced photonics and microelectronic device packaging, announced today they are offering a webinar focused on the many aspects to increasing manufacture throughput for semiconductor packaging: Throughput is More than Just Axis Speed.

In the world of automated semiconductor packaging, units-per-hour (UPH) and throughput are not just simple functions of any one machine's axis speed – rather they are the result of a much more complicated formula used to calculate the return on investment of semiconductor packaging equipment. In many scenarios, the potential maximum speed of a single system as documented in a brochure will be quite far away from the actual number of units produced. Throughput is a balance of many factors, including machine uptime, production yield, and serviceability/usability. In order to utilize each machine to its fullest in an autonomous line, several key considerations need to be calculated into the final UPH, and ultimately ROI:

- The capacity of, and downtime introduced with, each material handling step and associated automated equipment.
- The impact of process control steps on yield, material-waste-cost, and final effective units per hour.
- The effects of individual equipment's uptime on the productivity of the entire line.

By understanding these major factors, it is possible to calculate the true throughput for a given product and what machine specifications and capabilities are actually most important to pay attention to.

In this webinar, viewers will learn:

- The tradeoffs between automation equipment that leads to bottlenecks
- The importance of understanding the yield requirements
- How to maximize machine production time

The webinar is on June 29, 2022 at 8 am, PST. Registration for the webinar can be done here:

<https://www.palomartechnologies.com/webinar-registration-throughput-is-more-than-just-axis-speed>



About Palomar Technologies

Palomar Technologies makes the connected world possible by delivering a Total Process Solution™ for advanced photonic and microelectronic device assembly processes utilized in today's smart, connected devices. With a focus on flexibility, speed and accuracy, Palomar's Total Process Solution includes [Palomar die bonders](#), [Palomar wire and wedge bonders](#), [SST vacuum reflow systems](#), along with [Innovation Centers](#) for outsourced manufacturing and assembly, and [Customer Support](#) services, that together deliver improved quality and yield, reduced assembly times, and rapid ROI.

With its deep industry expertise, Palomar equips customers to become leaders in the development of complex, digital technologies that are the foundation of the connected world and the transmission of data generated by billions of connected devices. Palomar solutions are utilized by the world's leading companies providing solutions for datacom, 5G, electric vehicle power modules, autonomous vehicles/LiDAR, enhanced mobile broadband, Internet of Things, SMART technology, and mission-critical services.

Headquartered in Carlsbad, California, Palomar offers global sales, service and application support from its offices in the USA, Germany, Singapore, and China. For more information, visit: <http://www.palomartechnologies.com>

###

Media Contact:

Rebecca Janzon
Director of Marketing Communications
Email: rjanzon@bonders.com
Mobile: 760-409-7453